

TC74ACT574P, TC74ACT574F, TC74ACT574FW, TC74ACT574FT

OCTAL D – TYPE FLIP – FLOP WITH 3 – STATE OUTPUT

The TC74ACT574 is an advanced high speed CMOS OCTAL FLIP-FLOP fabricated with silicon gate and double-layer metal wiring C²MOS technology.

It achieves the high speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation.

This device may be used as a level converter for interfacing TTL or NMOS to High Speed CMOS. The inputs are compatible with TTL, NMOS and CMOS output voltage levels.

These 8-bit D-type flip-flops are controlled by a clock input (CK) and a output enable input ($\overline{OE}$).

When the $\overline{OE}$ input is high, the eight outputs are in a high impedance state.

All inputs are equipped with protection circuits against static discharge or transient excess voltage.

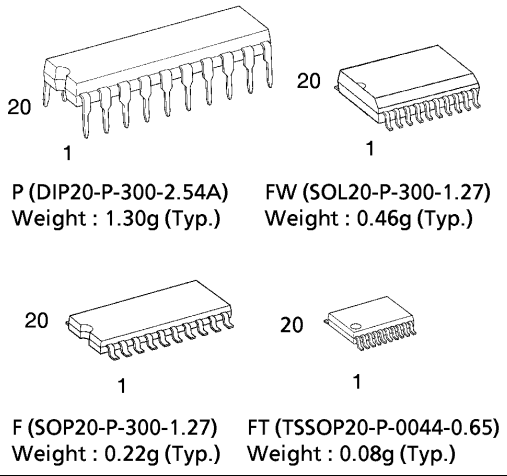
- FEATURES :
- High Speed..... $f_{MAX} = 180\text{MHz}$ (typ.)
at $V_{CC} = 5\text{V}$
 - Low Power Dissipation..... $I_{CC} = 8\mu\text{A}(\text{Max.})$ at $T_a = 25^{\circ}\text{C}$
 - Compatible with TTL outputs.... $V_{IL} = 0.8\text{V}(\text{Max.})$
 $V_{IH} = 2.0\text{V}(\text{Min.})$
 - Symmetrical Output Impedance... $|I_{OH}| = I_{OL} = 24\text{mA}(\text{Min.})$
Capability of driving 50Ω transmission lines.
 - Balanced Propagation Delays..... $t_{PLH} \approx t_{PHL}$
 - Pin and Function Compatible with 74F574

TRUTH TABLE

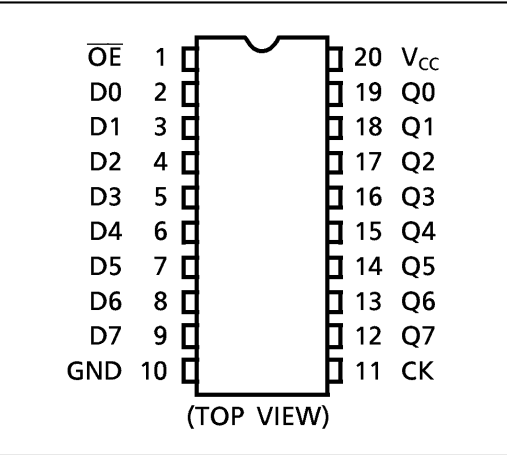
INPUTS			OUTPUTS
$\overline{OE}$	CK	D	Q
H	X	X	Z
L		X	Q_n
L		L	L
L		H	H

X : Don't Care
Z : High Impedance
 Q_n : No Change

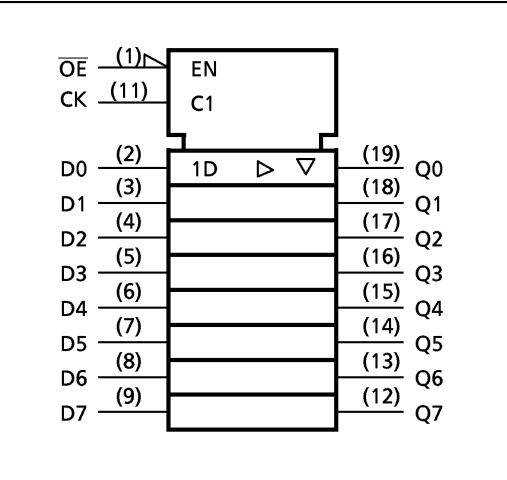
(Note) The JEDEC SOP (FW) is not available in Japan.



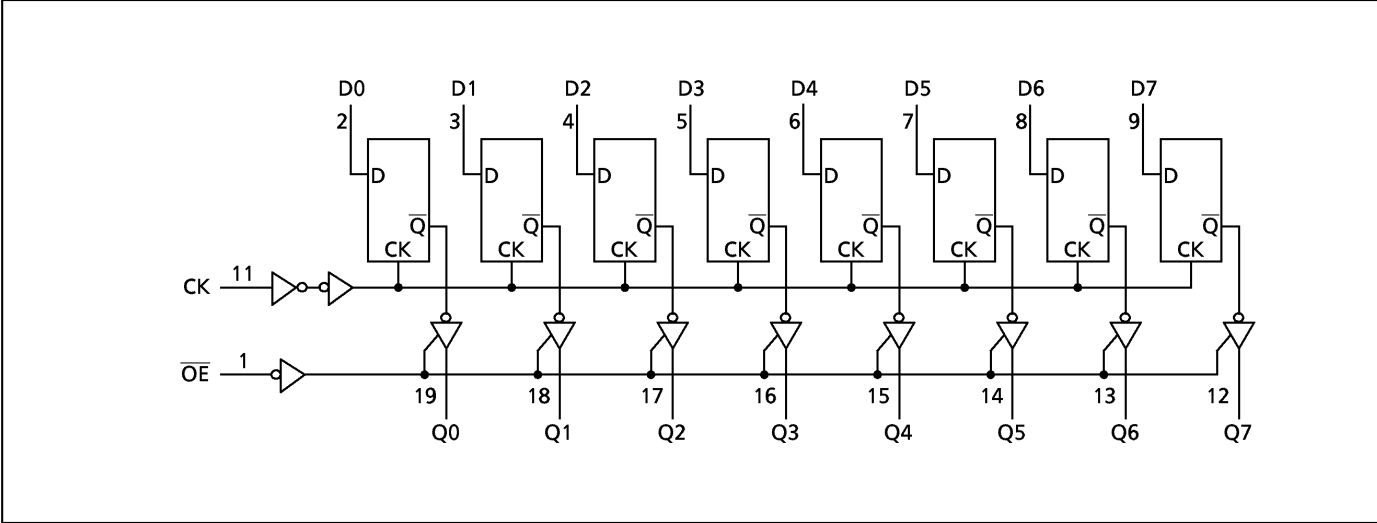
PIN ASSIGNMENT



IEC LOGIC SYMBOL



SYSTEM DIAGRAM



ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage Range	V_{CC}	$-0.5 \sim 7.0$	V
DC Input Voltage	V_{IN}	$-0.5 \sim V_{CC} + 0.5$	V
DC Output Voltage	V_{OUT}	$-0.5 \sim V_{CC} + 0.5$	V
Input Diode Current	I_{IK}	± 20	mA
Output Diode Current	I_{OK}	± 50	mA
DC Output Current	I_{OUT}	± 50	mA
DC V_{CC} /Ground Current	I_{CC}	± 200	mA
Power Dissipation	P_D	500 (DIP)* / 180 (SOP/TSSOP)	mW
Storage Temperature	T_{stg}	$-65 \sim 150$	$^{\circ}\text{C}$

*500mW in the range of $T_a = -40^{\circ}\text{C} \sim 65^{\circ}\text{C}$. From $T_a = 65^{\circ}\text{C}$ to 85°C a derating factor of $-10\text{mW}/^{\circ}\text{C}$ should be applied up to 300mW.

RECOMMENDED OPERATING CONDITIONS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage	V_{CC}	4.5~5.5	V
Input Voltage	V_{IN}	0~ V_{CC}	V
Output Voltage	V_{OUT}	0~ V_{CC}	V
Operating Temperature	T_{opr}	$-40 \sim 85$	$^{\circ}\text{C}$
Input Rise and Fall Time	dt / dV	0~10	ns / V

DC ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION		V _{CC} (V)	Ta = 25°C			Ta = -40~85°C		UNIT
					MIN.	TYP.	MAX.	MIN.	MAX.	
High - Level Input Voltage	V _{IH}			4.5 ┌ 5.5	2.0	—	—	2.0	—	V
Low - Level Input Voltage	V _{IL}			4.5 └ 5.5	—	—	0.8	—	0.8	V
High - Level Output Voltage	V _{OH}	V _{IN} = V _{IH} or V _{IL}	I _{OH} = -50μA I _{OH} = -24mA I _{OH} = -75mA*	4.5 4.5 5.5	4.4 3.94 —	4.5 — —	— — —	4.4 3.80 3.85	— — —	V
Low - Level Output Voltage	V _{OL}	V _{IN} = V _{IH} or V _{IL}	I _{OL} = 50μA I _{OL} = 24mA I _{OL} = 75mA*	4.5 4.5 5.5	— — —	0.0 — —	0.1 0.36 —	— — —	0.1 0.44 1.65	V
3 - State Output Off - State Current	I _{OZ}	V _{IN} = V _{IH} or V _{IL} V _{OUT} = V _{CC} or GND		5.5	—	—	±0.5	—	±5.0	μA
Input Leakage Current	I _{IN}	V _{IN} = V _{CC} or GND		5.5	—	—	±0.1	—	±1.0	
Quiescent Supply Current	I _{CC}	V _{IN} = V _{CC} or GND		5.5	—	—	8.0	—	80.0	
	I _C	PER INPUT : V _{IN} = 3.4V OTHER INPUT : V _{CC} or GND		5.5	—	—	1.35	—	1.5	mA

* : This spec indicates the capability of driving 50Ω transmission lines.
One output should be tested at a time for a 10ms maximum duration.

TIMING REQUIREMENTS (Input t_r = t_f = 3ns)

PARAMETER	SYMBOL	TEST CONDITION		Ta = 25°C	Ta = -40~85°C	UNIT
			V _{CC} (V)	LIMIT	LIMIT	
Minimum Pulse Width (CK)	t _{W(H)} t _{W(L)}		5.0 ± 0.5	5.0	5.0	ns
Minimum Set - up Time	t _s		5.0 ± 0.5	3.0	3.0	
Minimum Hold Time	t _h		5.0 ± 0.5	2.0	2.0	

AC ELECTRICAL CHARACTERISTICS ($C_L = 50\text{pF}$, $R_L = 500\Omega$, Input $t_r = t_f = 3\text{ns}$)

PARAMETER	SYMBOL	TEST CONDITION		Ta = 25°C			Ta = − 40~85°C		UNIT
			V _{CC} (V)	MIN.	TYP.	MAX.	MIN.	MAX.	
Propagation Delay Time (CK—Q)	t _{pLH} t _{pHL}		5.0 ± 0.5	—	6.2	10.1	1.0	11.5	ns
Output Enable Time	t _{pZL} t _{pZH}		5.0 ± 0.5	—	6.3	10.5	1.0	12.0	
Output Disable Time	t _{pLZ} t _{pHZ}		5.0 ± 0.5	—	6.6	9.6	1.0	11.0	
Maximum Clock Frequency	f _{MAX}		5.0 ± 0.5	85	160	—	85	—	MHz
Input Capacitance	C _{IN}			—	5	10	—	10	pF
Output Capacitance	C _{OUT}			—	10	—	—	—	
Power Dissipation Capacitance	C _{PD} (1)			—	33	—	—	—	

Note (1) C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

Average operating current can be obtained by the equation :

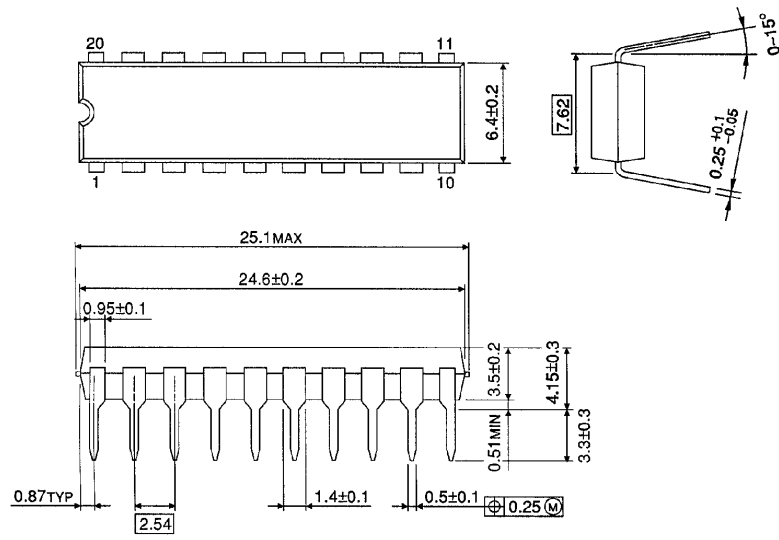
$$I_{CC}(\text{opr.}) = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC}/8 \text{ (per F/F)}$$

And the total C_{PD} when n pcs. of F/F operate can be gained by the following equation:

$$C_{PD}(\text{total}) = 21 + 12 \cdot n$$

DIP 20PIN PACKAGE DIMENSIONS (DIP20-P-300-2.54A)

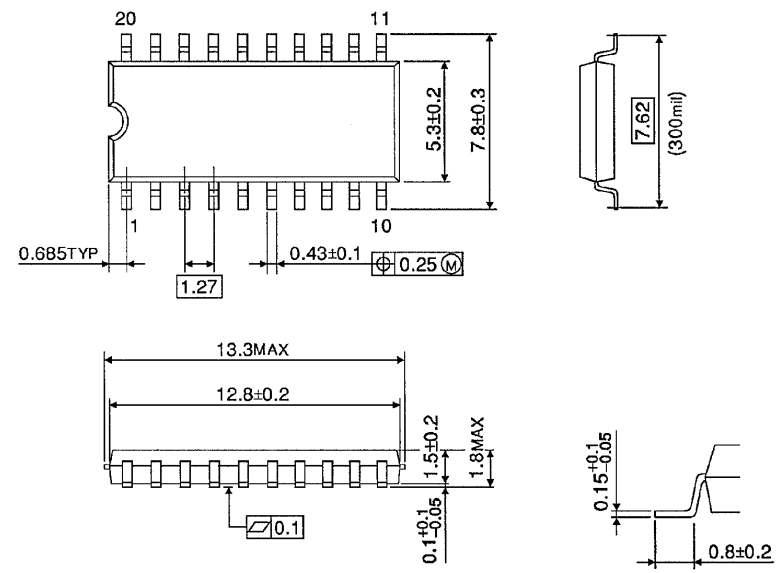
Unit in mm



Weight : 1.30g (Typ.)

SOP 20PIN (200mil BODY) PACKAGE DIMENSIONS (SOP20-P-300-1.27)

Unit in mm

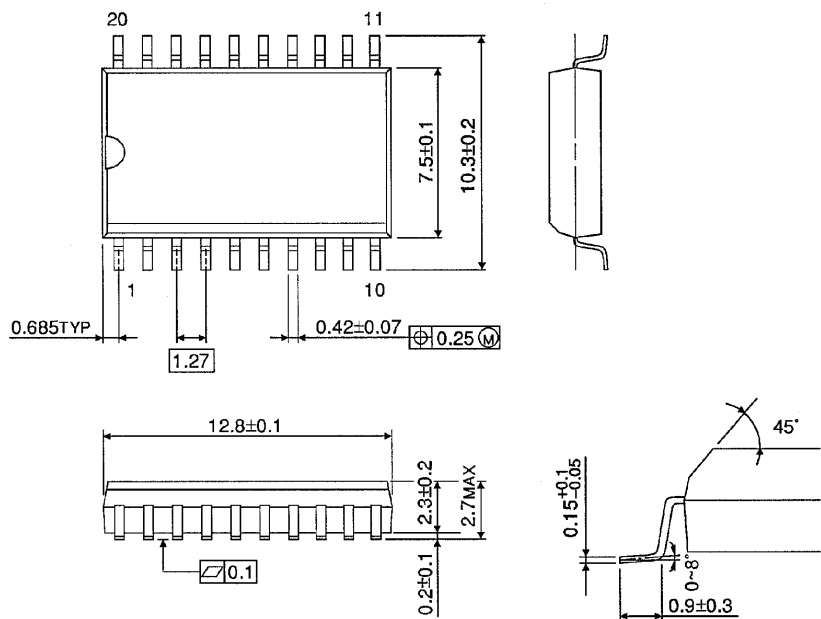


Weight : 0.22g (Typ.)

SOP 20PIN (300mil BODY) PACKAGE DIMENSIONS (SOL20-P-300-1.27)

Unit in mm

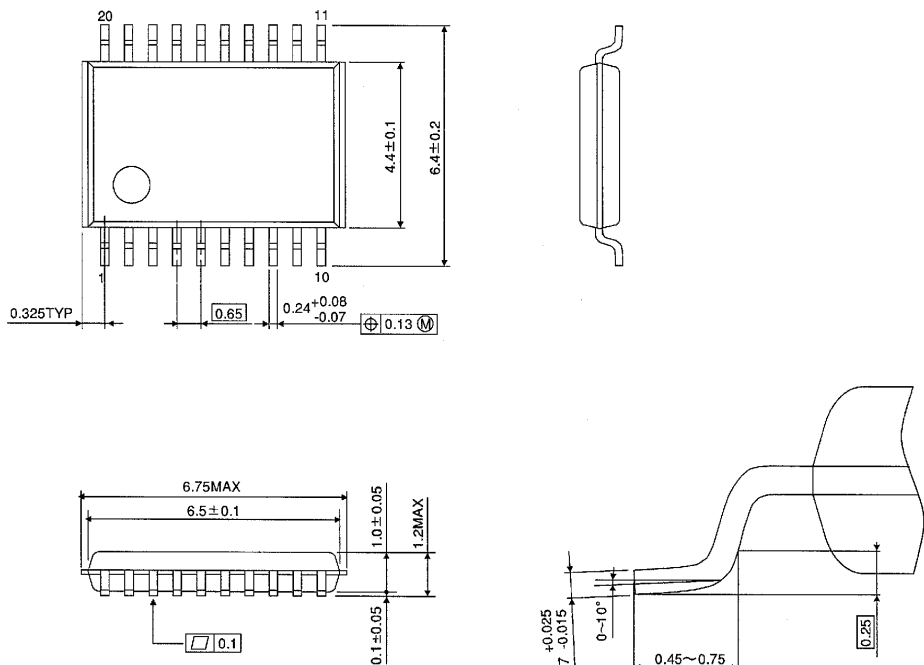
(Note) This package is not available in Japan.



Weight : 0.46g (Typ.)

TSSOP 20PIN PACKAGE DIMENSIONS (TSSOP20-P-0044-0.65)

Unit in mm



Weight : 0.08g (Typ.)

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